COURSE NAME: III BCA   **MAXIMUM MARKS: 50**

SEMESTER: V   **TIME: 3 HOURS**

PART-IV

SKILL BASED ELECTIVE-III

SUBJECT CODE – 22UBC5S1 TITLE: MOBILE PHONE SERVICES
SECTION-A (10X1=10 Marks)
ANSWER THE FOLLOWING QUESTIONS.
MULTIPLE CHOICE QUESTIONS.

1. When was mobile communication introduced?

    a) 1983   b) 1999   c) 1998   d)1967   **(K1)**

2. Which component is used to power the cell phone and needs to be recharged?

    a) Screen   b) Battery   c) Microphone   d) Button   **(K1)**

3. What is Mobile Repairing?

    a) To clean the PCB of a mobile phone b) To charge the battery of the mobile phone

    c) To hold the PCB of a mobile phone while soldering or repairing

    d) To test the voltage of the PCB components   **(K1)**

4. Identify the frequency of the crystal used for outgoing calls in mobile phones

    a) 26 MHz   b) 99 MHz   c) 108 MHz   d) 5.5 MHz   **(K1)**

5. Which type of maintenance is performed to correct error after the system has been deployed?

    a) Preventive Maintenance b) Adaptive Maintenance

    c) Corrective Maintenance d) Perfective Maintenance   **(K1)**

ANSWER THE FOLLOWING IN ONE (OR) TWO SENTENCES

6. What are the Components of investment using mobile repair?   **(K2)**

7. What are the key components of motherboard?   **(K2)**

8. What are the responsibilities of a mobile phone hardware repair technician?   **(K2)**

9. What is IC Problem in Mobile?   **(K2)**

10. In the context of mobile communication what is the full form of LTE?   **(K2)**

SECTION-B(5X8=40 MARKS)
ANSWER EITHER (a) OR (b) IN EACH OF THE FOLLOWING QUESTIONS.

11. a) Examine in details about various types of Mobile Phones and Technologies **(K4)**

(OR)

 b) Classify that Latest trend of mobile phones

12. a) Summarize about Integrated Circuit and BGA and AMD chips **(K5)**

(OR)

 b) Discuss in details about various types of Mobile Phone Parts

13. a) Classify and how to handling mobile phone repairing tools **(K4)**

(OR)

 b) Point out various professional Mobile phone repairing tools and Equipments

14. a) Discuss in details about Repairing procedure using Assembling and Disassembling mobile hardware repair services **(K5)**

(OR)

b) Summarize in details about Changes of different IC using Mobile hardware repair

15. a) classify about Mobile Software and Installation methods using Flashing **(K4)**

(OR)

b) Analyze about Fault finding and troubleshooting and antivirus installation and Mobile Bricking